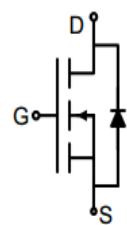
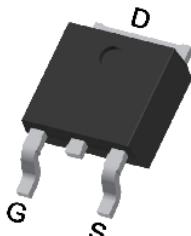


N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The G20N03K uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 30V ● I_D (at $V_{GS} = 10V$) 30A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 20mΩ ● $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 24mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-252</p>		
Device	Package	Marking	Packaging
G20N03K	TO-252	G20N03	2500pcs/Reel

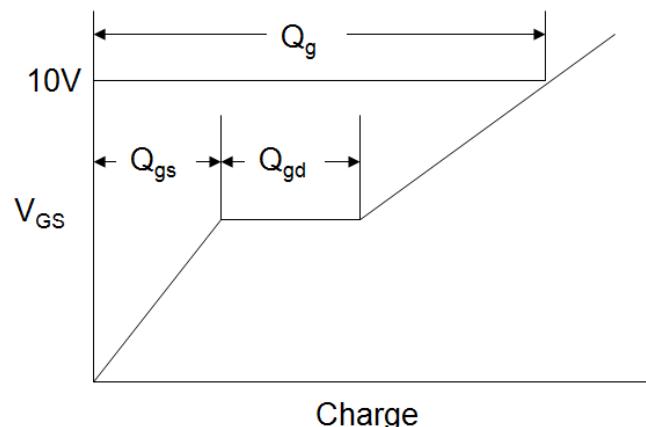
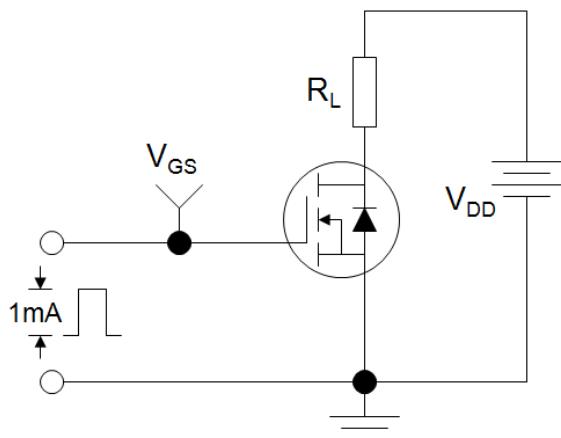
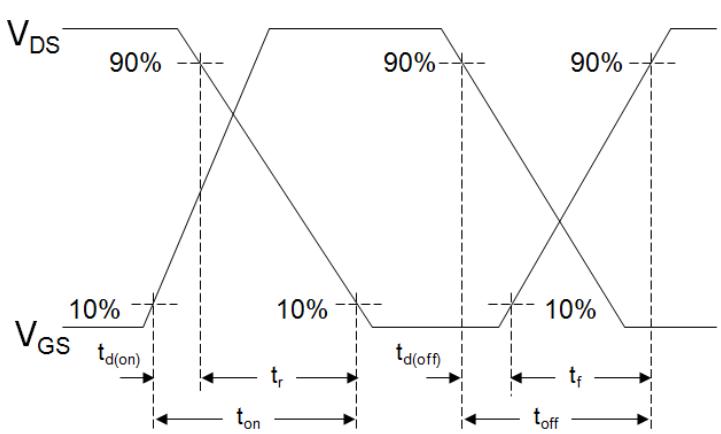
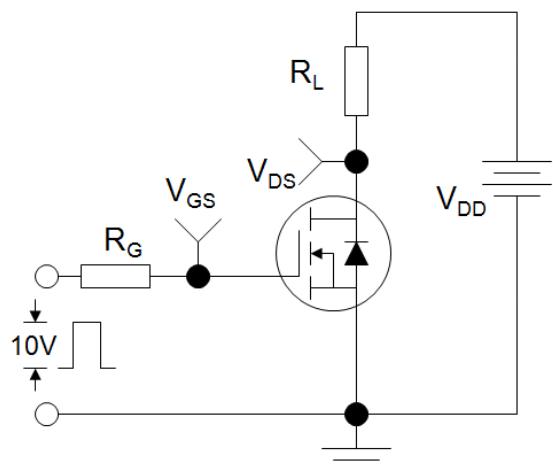
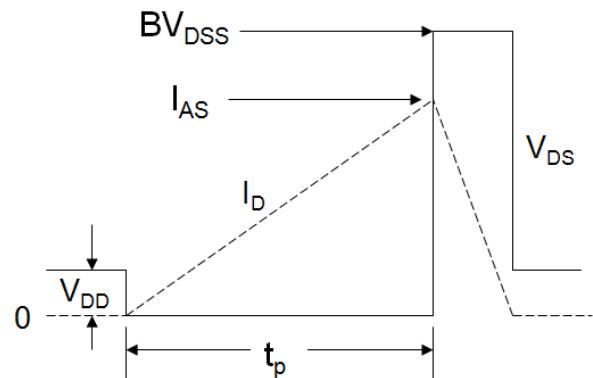
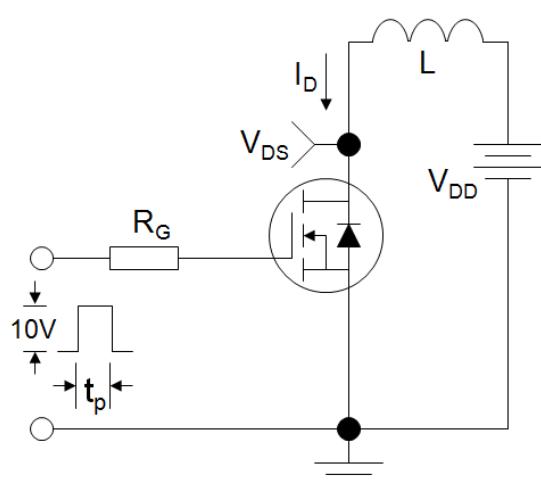
Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Continuous Drain Current	I_D	30	A
Pulsed Drain Current (note1)	I_{DM}	80	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	33	W
Single pulse avalanche energy (note3)	E_{AS}	31	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ\text{C}$
Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	3.8	$^\circ\text{C}/\text{W}$

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.5	2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	--	12	20	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 8\text{A}$	--	17	24	
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$	26	--	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1.0\text{MHz}$	--	923	--	pF
Output Capacitance	C_{oss}		--	100	--	
Reverse Transfer Capacitance	C_{rss}		--	94	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 15\text{V}, I_D = 10\text{A}, V_{\text{GS}} = 10\text{V}$	--	18	--	nC
Gate-Source Charge	Q_{gs}		--	3	--	
Gate-Drain Charge	Q_{gd}		--	4	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 10\text{A}, R_G = 3\Omega$	--	5	--	ns
Turn-on Rise Time	t_r		--	12	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	19	--	
Turn-off Fall Time	t_f		--	6	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	30	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 10\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Time	Tr_{rr}	$I_S = 10\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	19	--	ns
Reverse Recovery Charge	Q_{rr}		--	10	--	nC

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G
3. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$

Gate Charge Test Circuit**Switch Time Test Circuit****EAS Test Circuit**

Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

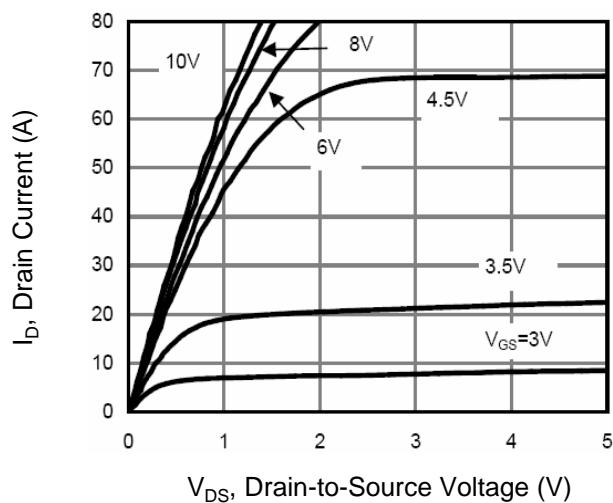


Figure 2. Transfer Characteristics

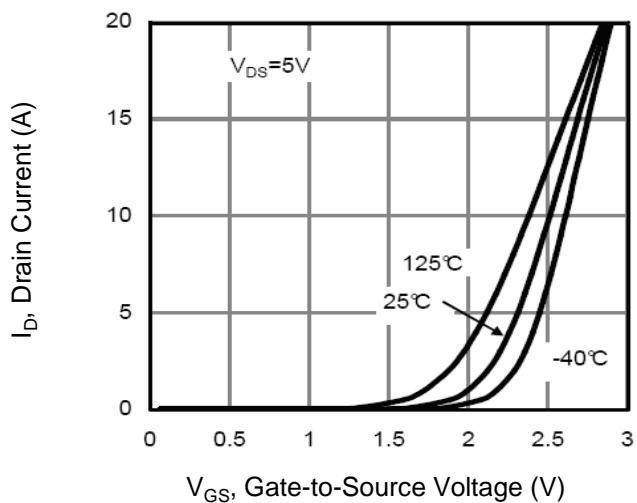


Figure 3. Gate Charge

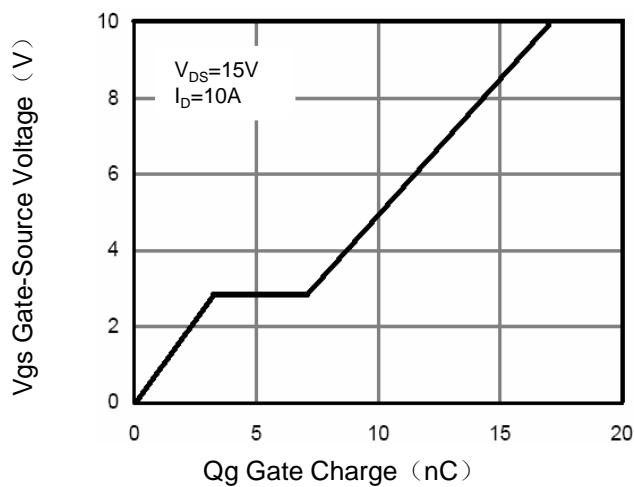


Figure 4. Drain Source On Resistance

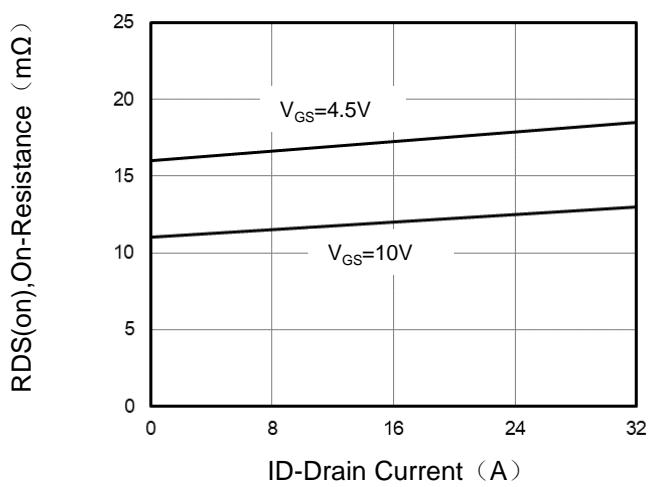


Figure 5. Capacitance

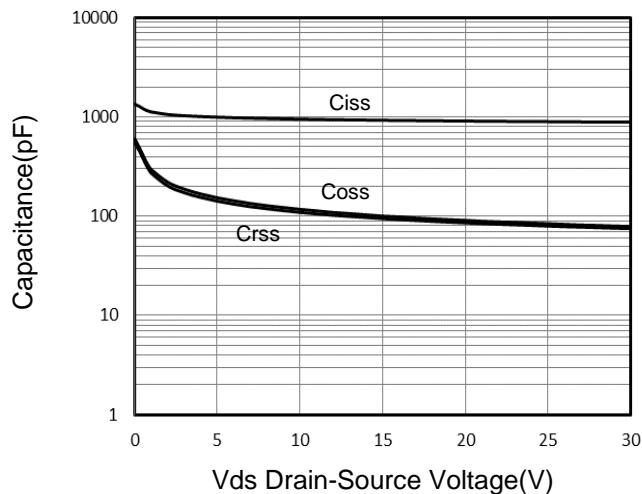
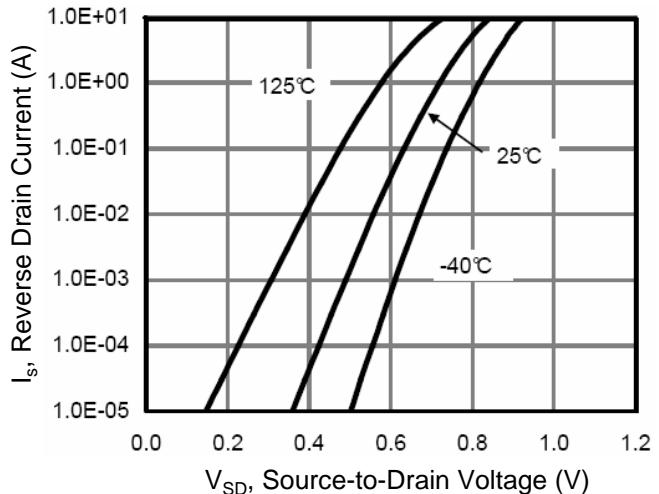


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

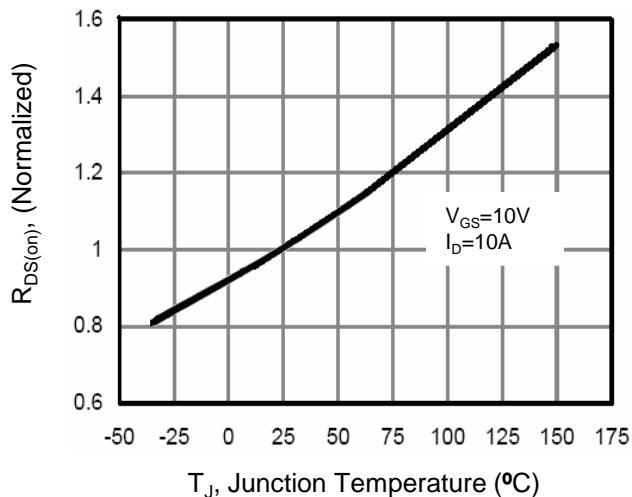


Figure 8. Safe Operation Area

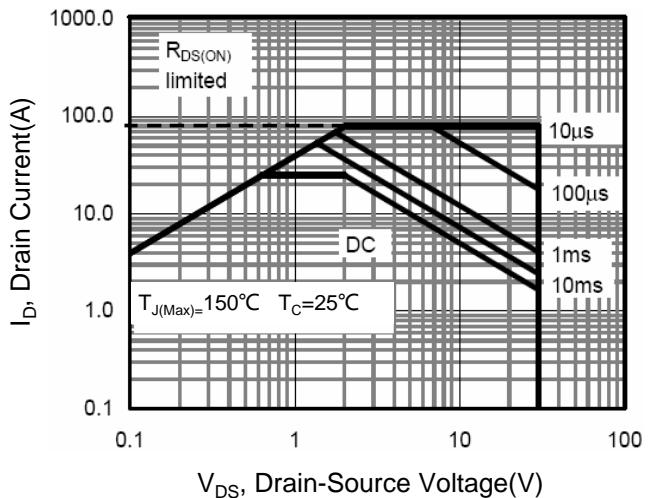
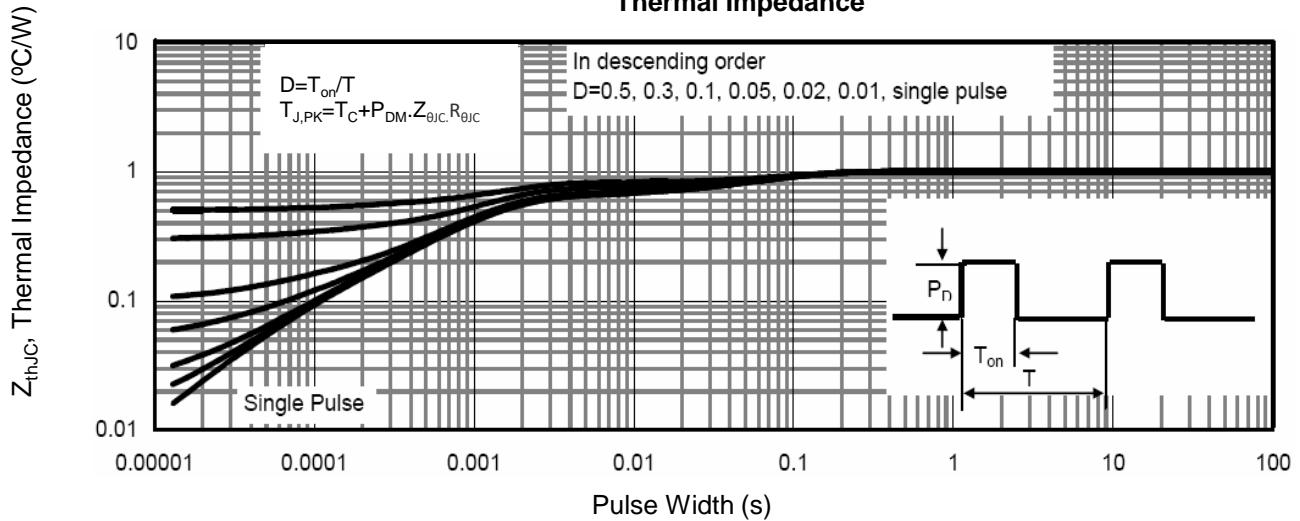
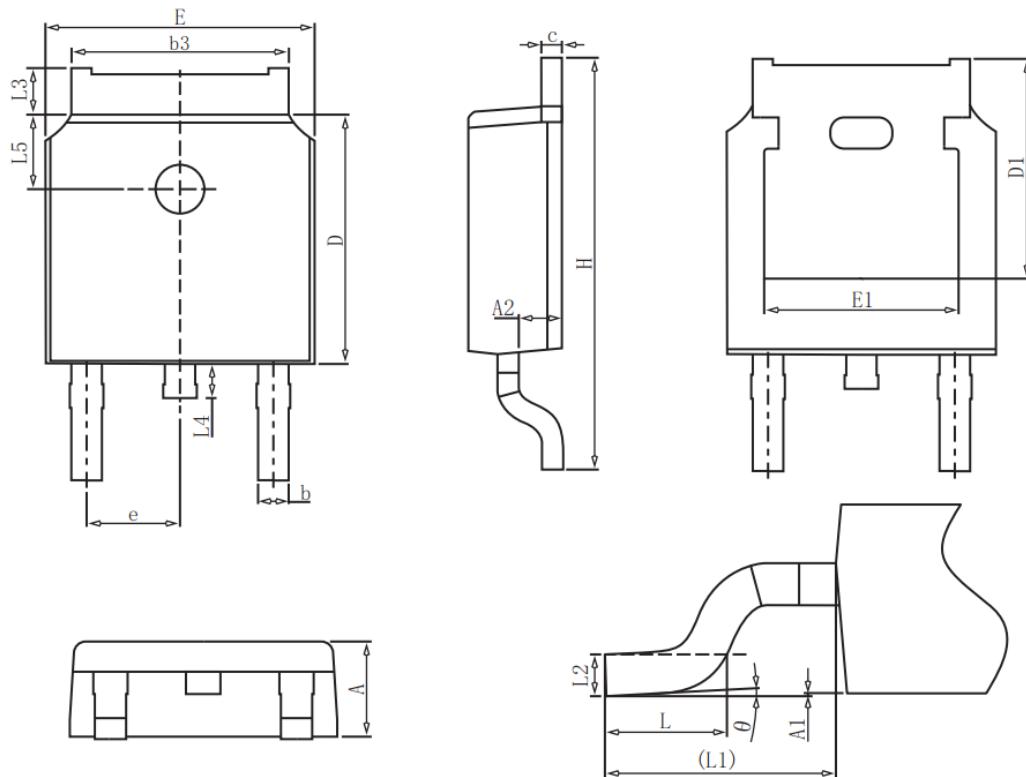


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-252 Package Information



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	2.2	2.3	2.4
A1	0		0.2
A2	0.97	1.07	1.17
b	0.68	0.78	0.9
b3	5.2	5.33	5.5
c	0.43	0.53	0.63
D	5.98	6.1	6.22
D1	5.30REF		
E	6.4	6.6	6.8
E1	4.63		
e	2.286BSC		
H	9.4	10.1	10.5
L	1.38	1.5	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88		1.28
L4	0.5		1
L5	1.65	1.8	1.95
θ	0°		8°